



**THE DATASHEET OF
IGW100N60H3FKSA1**



IGBT

High speed IGBT in Trench and Fieldstop technology

IGW100N60H3

600V high speed switching series third generation

Data sheet

Industrial Power Control

High speed IGBT in Trench and Fieldstop technology

Features:

TRENCHSTOP™ technology offering

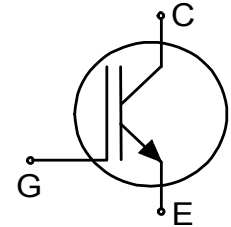
- very low turn-off energy
- low V_{CEsat}
- low EMI
- maximum junction temperature 175°C
- qualified according to JEDEC for target applications
- Pb-free lead plating, halogen-free mould compound, RoHS compliant
- complete product spectrum and PSpice Models:
<http://www.infineon.com/igbt/>

Applications:

- uninterruptible power supplies
- welding converters
- converters with high switching frequency

Package pin definition:

- Pin 1 - gate
- Pin 2 & backside - collector
- Pin 3 - emitter



Key Performance and Package Parameters

| Type | V_{CE} | I_C | $V_{CEsat}, T_{vj}=25^\circ\text{C}$ | T_{vjmax} | Marking | Package |
|-------------|----------|-------|--------------------------------------|-------------|----------|-----------------|
| IGW100N60H3 | 600V | 100A | 1.85V | 175°C | G100H603 | PG-TO247-pin123 |



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Maximum ratings

| Parameter | Symbol | Value | Unit |
|---|-------------|----------------|------------------|
| Collector-emitter voltage | V_{CE} | 600 | V |
| DC collector current, limited by $T_{vjmax}^{1)}$ $T_C = 25^\circ\text{C}$ value limited by bondwire $T_C = 100^\circ\text{C}$ | I_C | 140.0 120.0 | A |
| Pulsed collector current, t_p limited by $T_{vjmax}^{2)}$ | I_{Cpuls} | 300.0 | A |
| Turn off safe operating area $V_{CE} \leq 600\text{V}$, $T_{vj} \leq 175^\circ\text{C}^{3)}$ | - | 300.0 | A |
| Gate-emitter voltage | V_{GE} | ± 20 | V |
| Short circuit withstand time $V_{GE} = 15.0\text{V}$, $V_{CC} \leq 400\text{V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{s}$ $T_{vj} = 150^\circ\text{C}$ | t_{SC} | 5 | μs |
| Power dissipation $T_C = 25^\circ\text{C}$ | P_{tot} | 714.0 | W |
| Operating junction temperature | T_{vj} | -40...+175 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55...+150 | $^\circ\text{C}$ |
| Soldering temperature, wave soldering 1.6 mm (0.063 in.) from case for 10s | | 260 | $^\circ\text{C}$ |
| Mounting torque, M3 screw Maximum of mounting processes: 3 | M | 0.6 | Nm |

Thermal Resistance

| Parameter | Symbol | Conditions | Max. Value | Unit |
|---|---------------|------------|------------|------|
| Characteristic | | | | |
| IGBT thermal resistance, ⁴⁾ junction - case | $R_{th(j-c)}$ | | 0.21 | K/W |
| Thermal resistance junction - ambient | $R_{th(j-a)}$ | | 40 | K/W |

Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | | | Unit |
|--------------------------------------|---------------|--|-------------|----------------------|----------------|---------------|
| | | | min. | typ. | max. | |
| Collector-emitter breakdown voltage | $V_{(BR)CES}$ | $V_{GE} = 0\text{V}$, $I_C = 2.00\text{mA}$ | 600 | - | - | V |
| Collector-emitter saturation voltage | V_{CEsat} | $V_{GE} = 15.0\text{V}$, $I_C = 100.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$ | - - - | 1.85 2.10 2.25 | 2.30 - - | V |
| Gate-emitter threshold voltage | $V_{GE(th)}$ | $I_C = 1.60\text{mA}$, $V_{CE} = V_{GE}$ | 4.1 | 5.1 | 5.7 | V |
| Zero gate voltage collector current | I_{CES} | $V_{CE} = 600\text{V}$, $V_{GE} = 0\text{V}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$ | - - | - - | 40.0 6700.0 | μA |
| Gate-emitter leakage current | I_{GES} | $V_{CE} = 0\text{V}$, $V_{GE} = 20\text{V}$ | - | - | 100 | nA |
| Transconductance | g_{fs} | $V_{CE} = 20\text{V}$, $I_C = 100.0\text{A}$ | - | 50.0 | - | S |

¹⁾ For maximal distance of 5mm between soldering point and mould

²⁾ Additionally $t_p < 10\text{ms}$ due to bondwire

³⁾ Additionally $t_p < 10\text{ms}$ due to bondwire

⁴⁾ Thermal resistance of grease $R_{th(c-s)}$ (case to heat sink) more than 0.1 K/W not included.

Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | | | Unit |
|--|-------------|--|-------|-------|------|------|
| | | | min. | typ. | max. | |
| Dynamic Characteristic | | | | | | |
| Input capacitance | C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | - | 6100 | - | pF |
| Output capacitance | C_{oes} | | - | 210 | - | |
| Reverse transfer capacitance | C_{res} | | - | 180 | - | |
| Gate charge | Q_G | $V_{CC} = 480\text{V}, I_C = 100.0\text{A}, V_{GE} = 15\text{V}$ | - | 625.0 | - | nC |
| Short circuit collector current Max. 1000 short circuits Time between short circuits: $\geq 1.0\text{s}$ | $I_{C(SC)}$ | $V_{GE} = 15.0\text{V}, V_{CC} \leq 400\text{V}, t_{SC} \leq 5\mu\text{s}, T_{vj} = 150^{\circ}\text{C}$ | - | 890 | - | A |

Switching Characteristic, Inductive Load

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------|--------|------------|-------|------|------|------|
| | | | min. | typ. | max. | |

IGBT Characteristic, at $T_{vj} = 25^{\circ}\text{C}$

| | | | | | | |
|------------------------|--------------|---|---|------|---|----|
| Turn-on delay time | $t_{d(on)}$ | $T_{vj} = 25^{\circ}\text{C}, V_{CC} = 400\text{V}, I_C = 100.0\text{A}, V_{GE} = 0.0/15.0\text{V}, r_G = 3.5\Omega, L\sigma = 25\text{nH}, C\sigma = 50\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode (IDW50E60) reverse recovery. | - | 30 | - | ns |
| Rise time | t_r | | - | 47 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 265 | - | ns |
| Fall time | t_f | | - | 30 | - | ns |
| Turn-on energy | E_{on} | | - | 3.70 | - | mJ |
| Turn-off energy | E_{off} | | - | 1.90 | - | mJ |
| Total switching energy | E_{ts} | | - | 5.60 | - | mJ |

Switching Characteristic, Inductive Load

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------|--------|------------|-------|------|------|------|
| | | | min. | typ. | max. | |

IGBT Characteristic, at $T_{vj} = 175^{\circ}\text{C}$

| | | | | | | |
|------------------------|--------------|--|---|------|---|----|
| Turn-on delay time | $t_{d(on)}$ | $T_{vj} = 175^{\circ}\text{C}, V_{CC} = 400\text{V}, I_C = 100.0\text{A}, V_{GE} = 0.0/15.0\text{V}, r_G = 3.5\Omega, L\sigma = 25\text{nH}, C\sigma = 50\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode (IDW50E60) reverse recovery. | - | 28 | - | ns |
| Rise time | t_r | | - | 44 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 310 | - | ns |
| Fall time | t_f | | - | 23 | - | ns |
| Turn-on energy | E_{on} | | - | 4.70 | - | mJ |
| Turn-off energy | E_{off} | | - | 2.30 | - | mJ |
| Total switching energy | E_{ts} | | - | 7.00 | - | mJ |

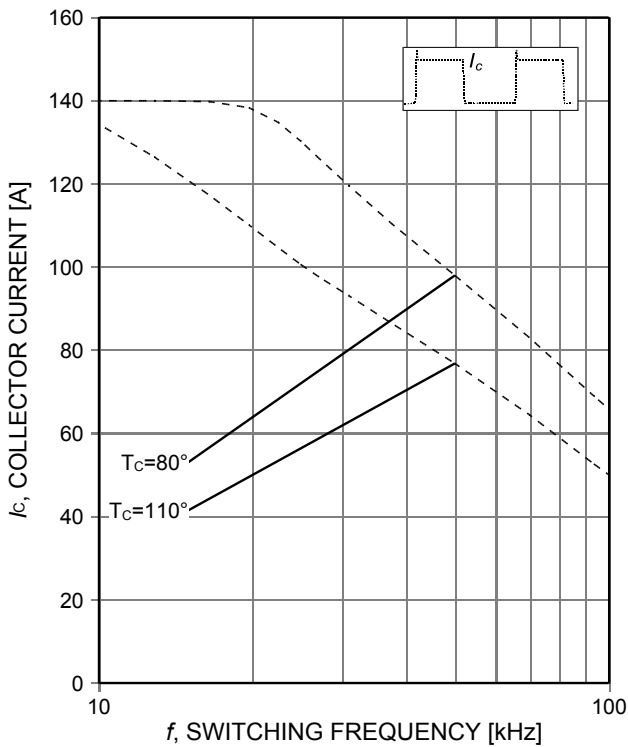


Figure 1. **Collector current as a function of switching frequency**
 ($T_{vj} \leq 175^\circ\text{C}$, $D=0.5$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$,
 $r_G=3.5\Omega$, $R_{th(j-c)}=0.21\text{K/W}$)

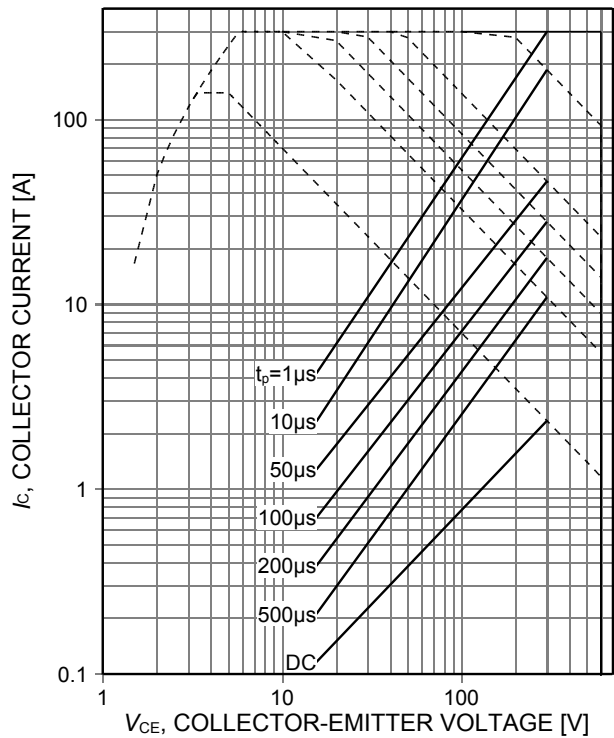


Figure 2. **Forward bias safe operating area**
 ($D=0$, $T_C=25^\circ\text{C}$, $T_{vj} \leq 175^\circ\text{C}$; $V_{GE}=15\text{V}$,
 $R_{th(j-c)}=0.21\text{K/W}$)

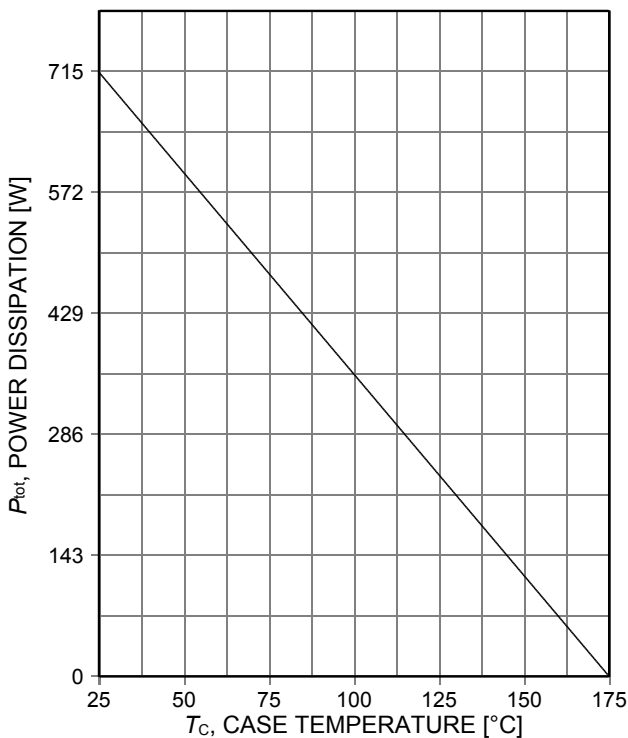


Figure 3. **Power dissipation as a function of case temperature**
 ($T_{vj} \leq 175^\circ\text{C}$, $R_{th(j-c)}=0.21\text{K/W}$)

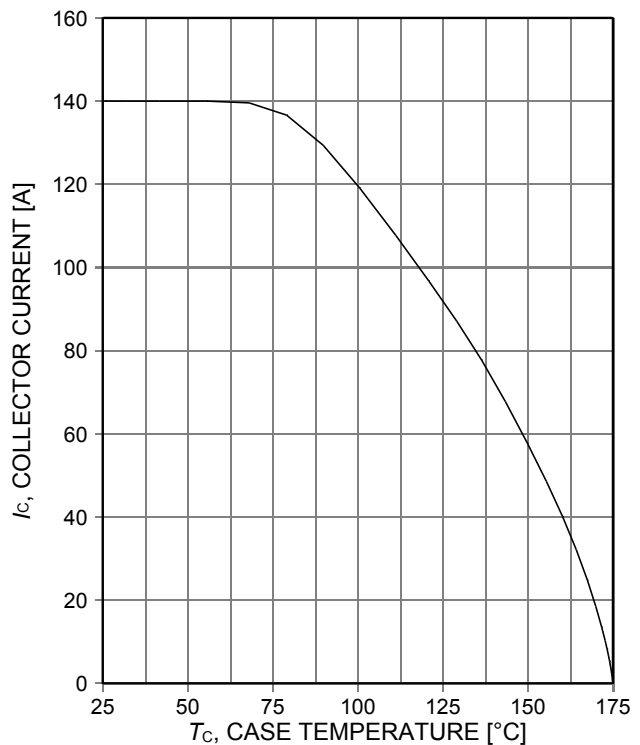


Figure 4. **Collector current as a function of case temperature**
 ($V_{GE} \geq 15\text{V}$, $T_{vj} \leq 175^\circ\text{C}$, $R_{th(j-c)}=0.21\text{K/W}$)

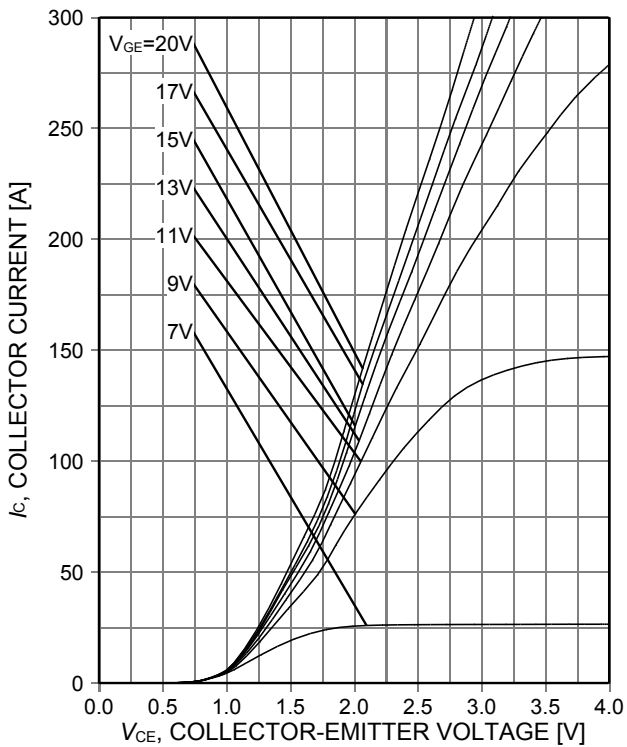


Figure 5. **Typical output characteristic**
($T_{vj}=25^{\circ}\text{C}$)

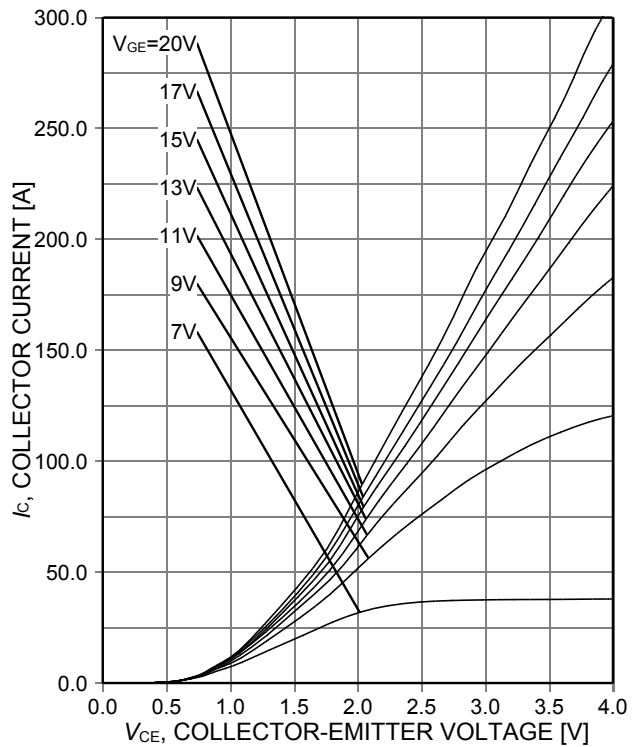


Figure 6. **Typical output characteristic**
($T_{vj}=175^{\circ}\text{C}$)

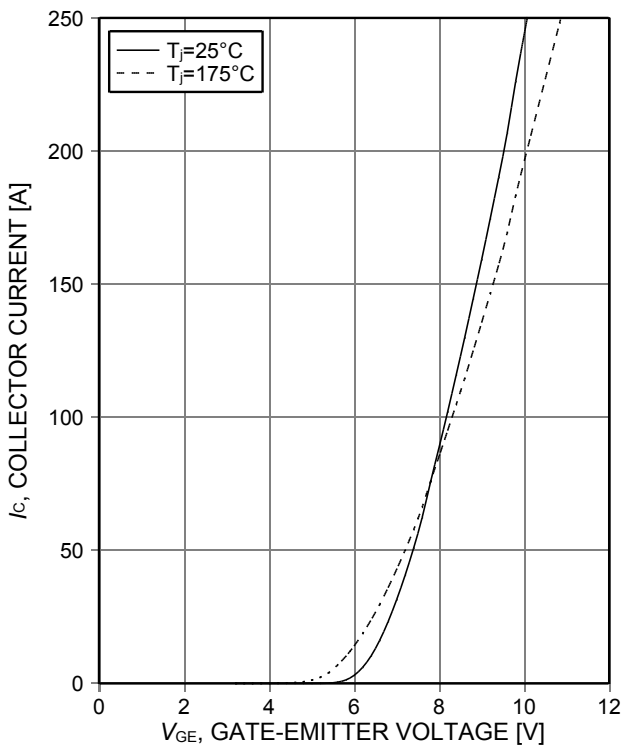


Figure 7. **Typical transfer characteristic**
($V_{ce}=20\text{V}$)

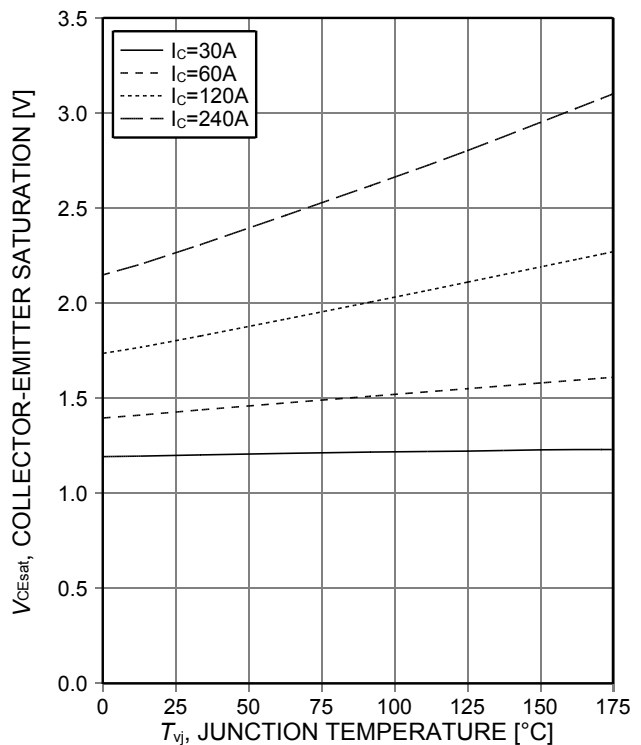


Figure 8. **Typical collector-emitter saturation voltage as a function of junction temperature**
($V_{ge}=15\text{V}$)

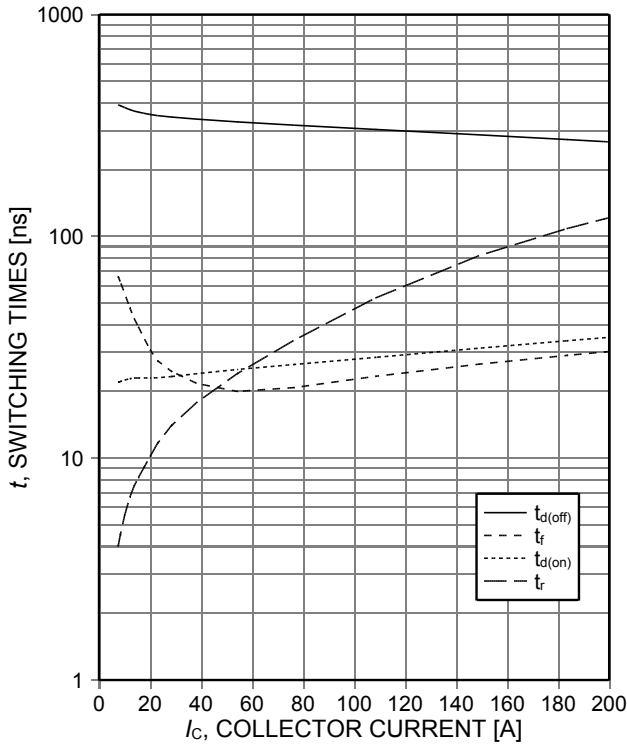


Figure 9. **Typical switching times as a function of collector current**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $r_G=3.5\Omega$, Dynamic test circuit in Figure E)

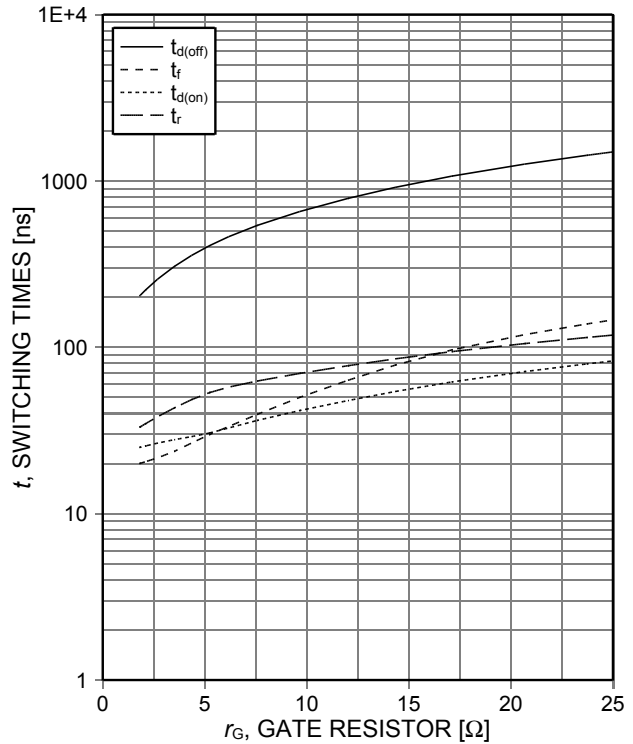


Figure 10. **Typical switching times as a function of gate resistor**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=100\text{A}$, Dynamic test circuit in Figure E)

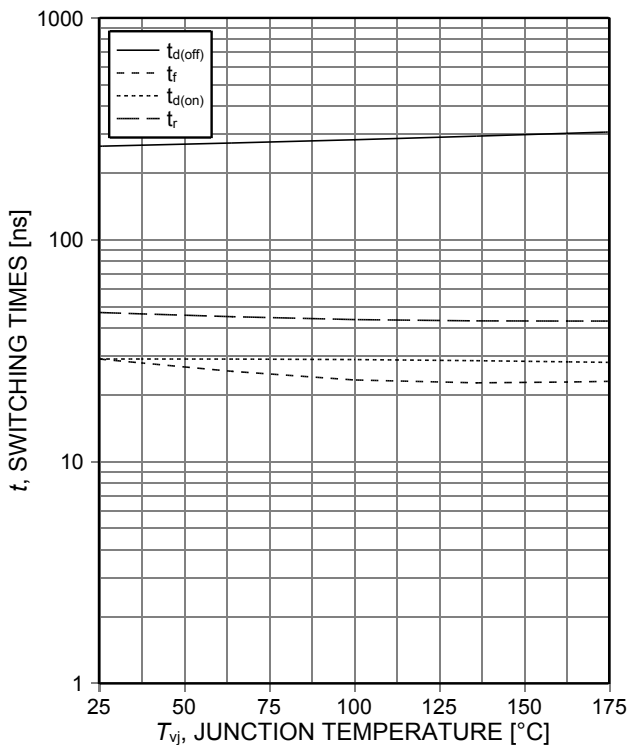


Figure 11. **Typical switching times as a function of junction temperature**
 (inductive load, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=100\text{A}$, $r_G=3.5\Omega$, Dynamic test circuit in Figure E)

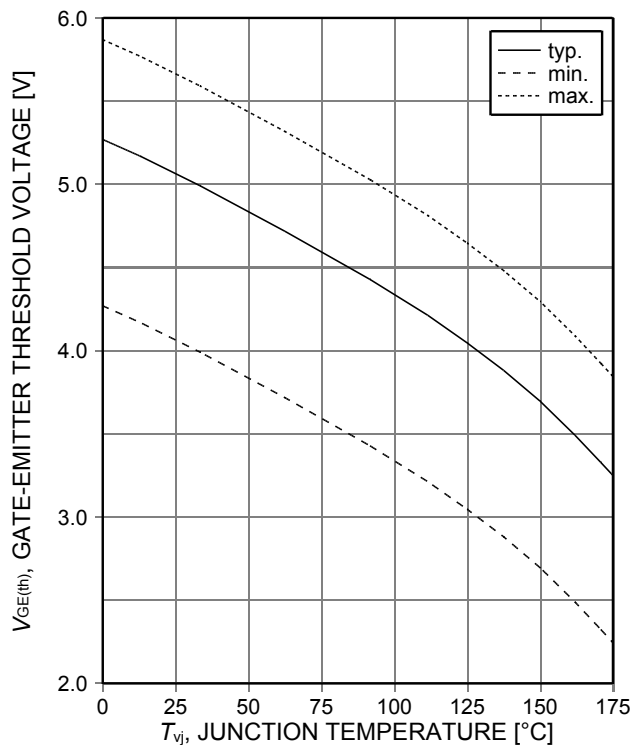


Figure 12. **Gate-emitter threshold voltage as a function of junction temperature**
 ($I_C=1.6\text{mA}$)

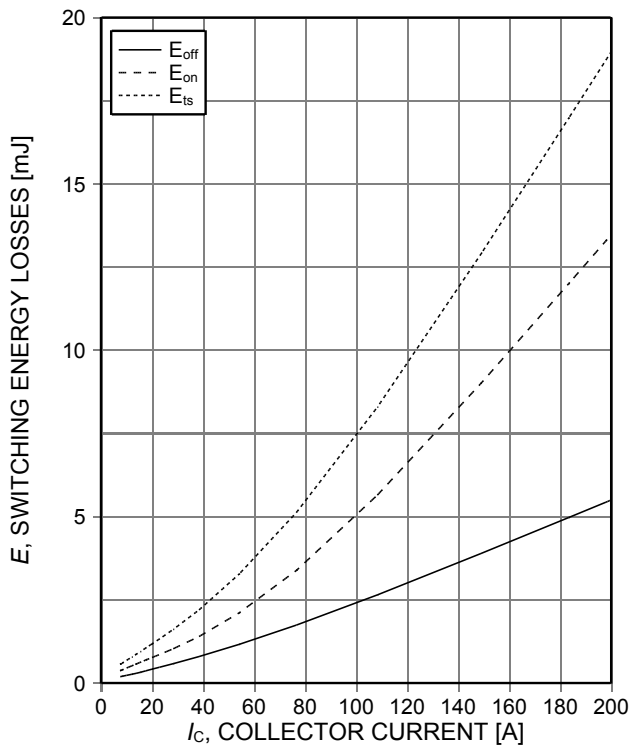


Figure 13. **Typical switching energy losses as a function of collector current**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $r_G=3.5\Omega$, Dynamic test circuit in Figure E)

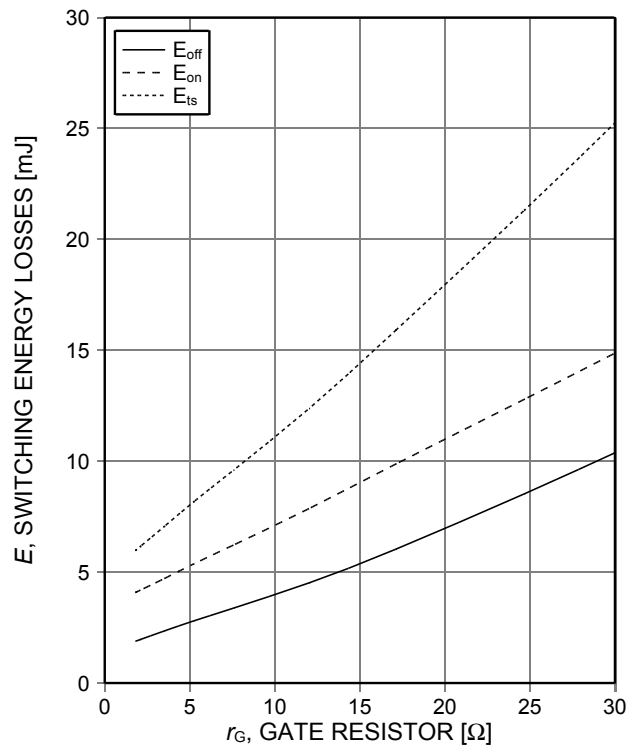


Figure 14. **Typical switching energy losses as a function of gate resistor**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_c=100\text{A}$, Dynamic test circuit in Figure E)

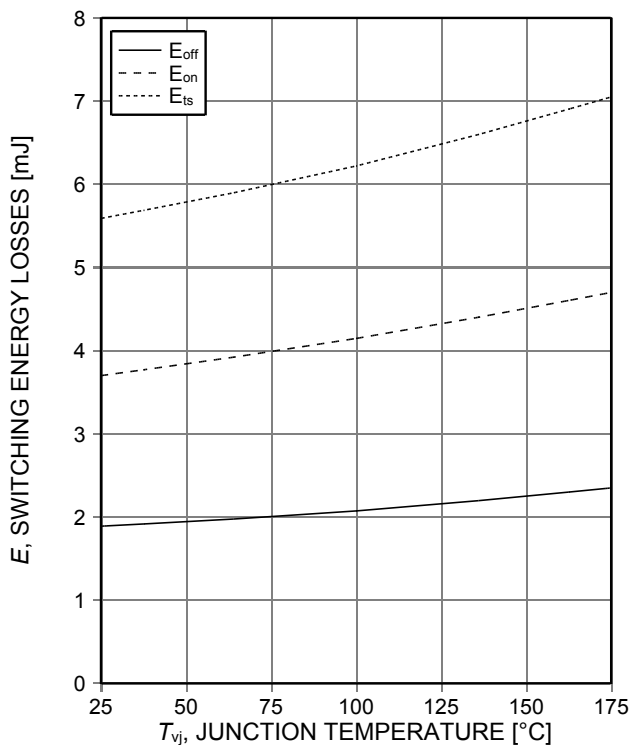


Figure 15. **Typical switching energy losses as a function of junction temperature**
 (inductive load, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_c=100\text{A}$, $r_G=3.5\Omega$, Dynamic test circuit in Figure E)

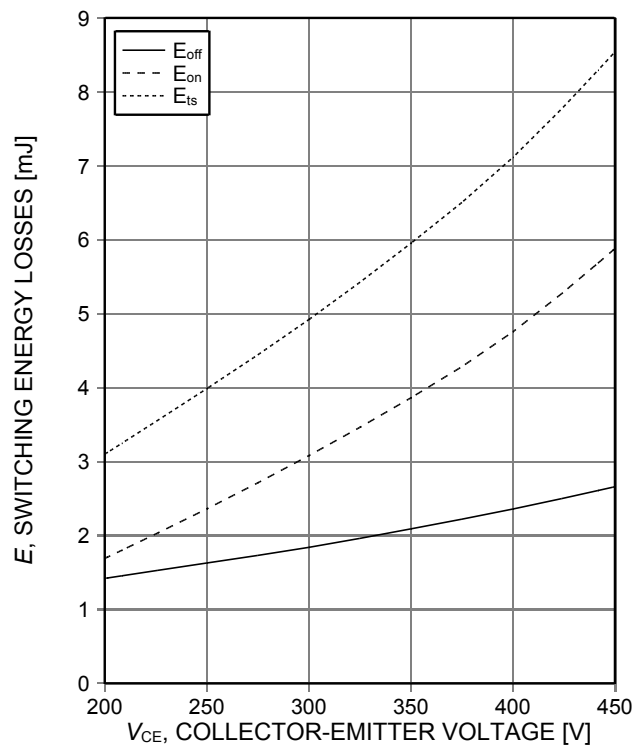


Figure 16. **Typical switching energy losses as a function of collector emitter voltage**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{GE}=15/0\text{V}$, $I_c=100\text{A}$, $r_G=3.5\Omega$, Dynamic test circuit in Figure E)

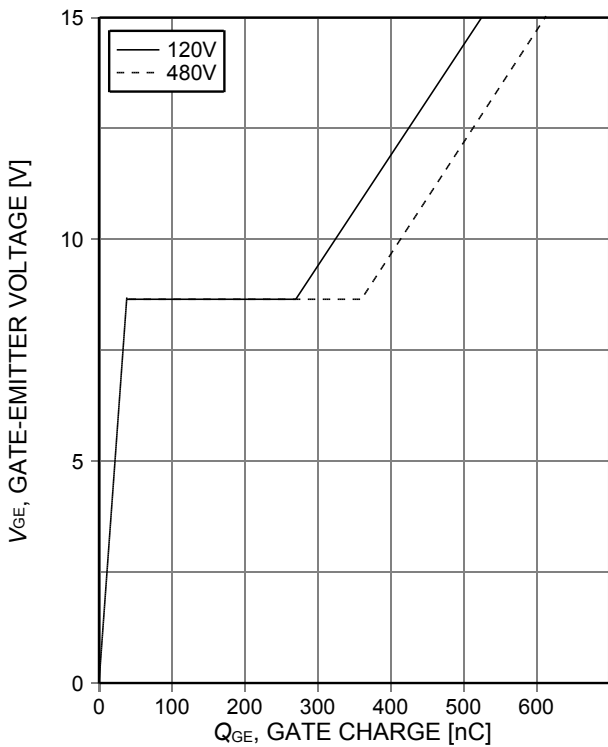


Figure 17. **Typical gate charge**
($I_C=100A$)

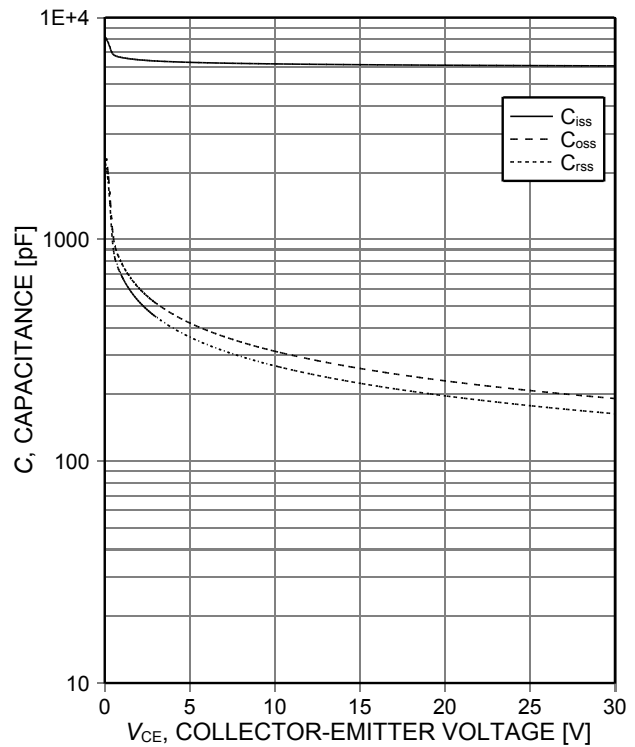


Figure 18. **Typical capacitance as a function of collector-emitter voltage**
($V_{GE}=0V$, $f=1MHz$)

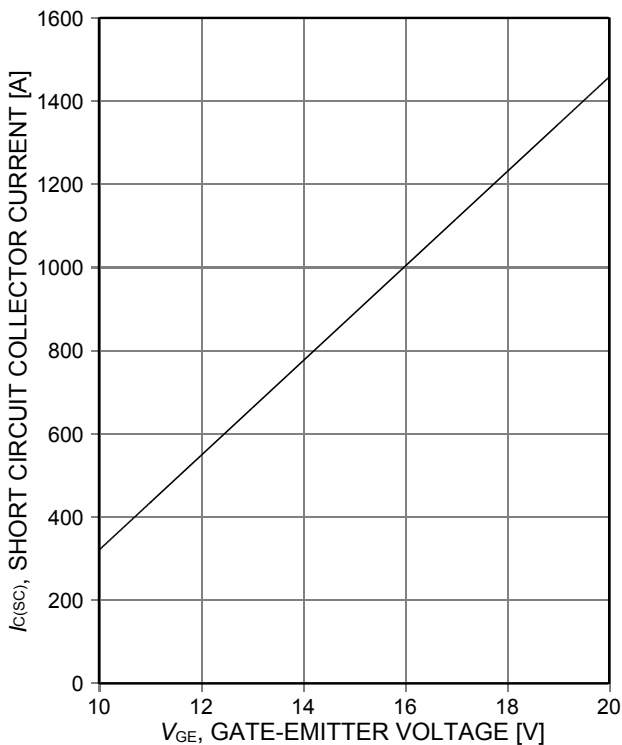


Figure 19. **Typical short circuit collector current as a function of gate-emitter voltage**
($V_{CE}\leq 400V$, $T_{vj}\leq 150^\circ C$)

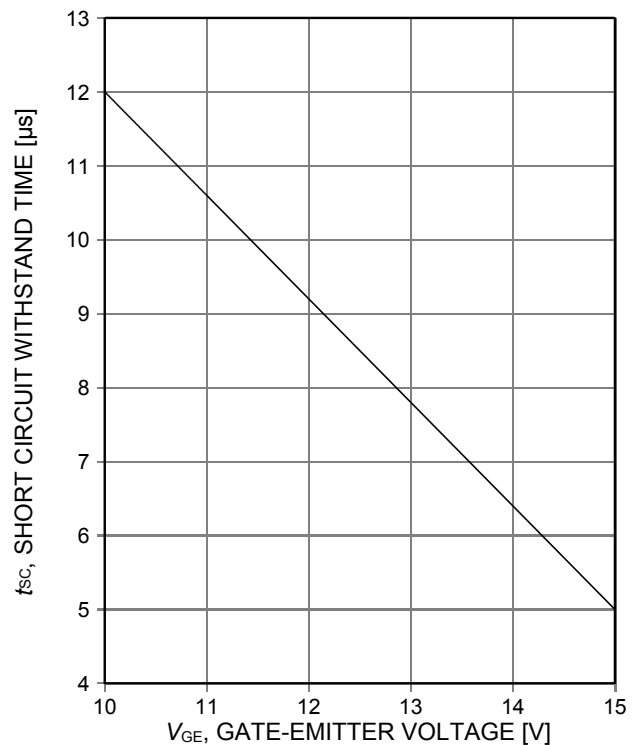


Figure 20. **Short circuit withstand time as a function of gate-emitter voltage**
($V_{CE}\leq 400V$, start at $T_{vj}\leq 150^\circ C$)

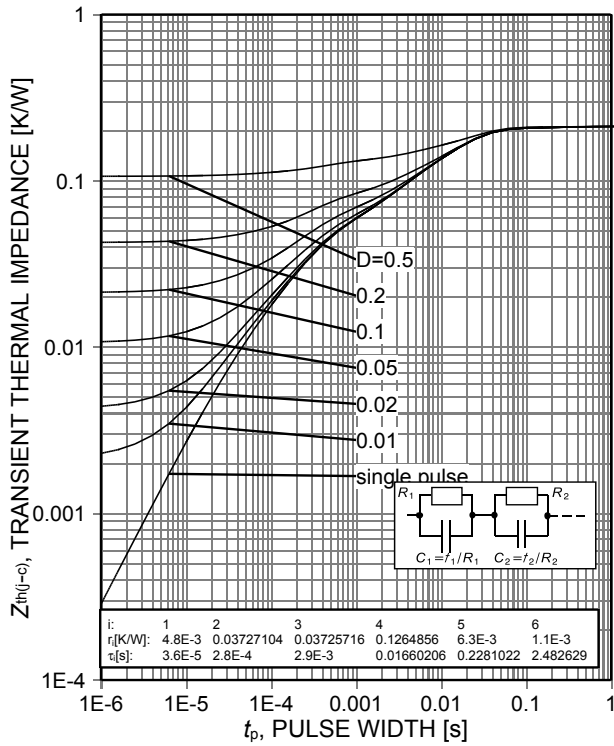
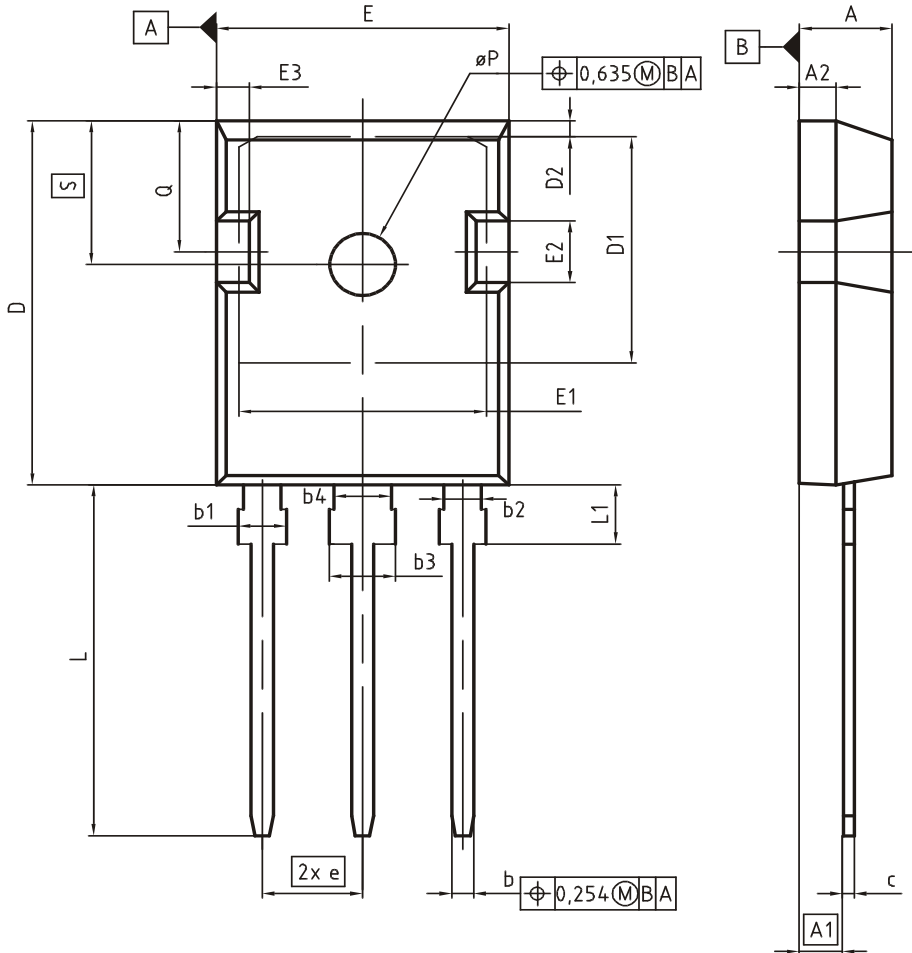


Figure 21. IGBT transient thermal impedance ($D=t_p/T$)

PG-TO247-3



| DIM | MILLIMETERS | | INCHES | |
|----------|-------------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.83 | 5.21 | 0.190 | 0.205 |
| A1 | 2.27 | 2.54 | 0.089 | 0.100 |
| A2 | 1.85 | 2.16 | 0.073 | 0.085 |
| b | 1.07 | 1.33 | 0.042 | 0.052 |
| b1 | 1.90 | 2.41 | 0.075 | 0.095 |
| b2 | 1.90 | 2.16 | 0.075 | 0.085 |
| b3 | 2.87 | 3.38 | 0.113 | 0.133 |
| b4 | 2.87 | 3.13 | 0.113 | 0.123 |
| c | 0.55 | 0.68 | 0.022 | 0.027 |
| D | 20.80 | 21.10 | 0.819 | 0.831 |
| D1 | 16.25 | 17.65 | 0.640 | 0.695 |
| D2 | 0.95 | 1.35 | 0.037 | 0.053 |
| E | 15.70 | 16.13 | 0.618 | 0.635 |
| E1 | 13.10 | 14.15 | 0.516 | 0.557 |
| E2 | 3.68 | 5.10 | 0.145 | 0.201 |
| E3 | 1.00 | 2.60 | 0.039 | 0.102 |
| e | 5.44 (BSC) | | 0.214 (BSC) | |
| N | 3 | | 3 | |
| L | 19.80 | 20.32 | 0.780 | 0.800 |
| L1 | 4.10 | 4.47 | 0.161 | 0.176 |
| ϕP | 3.50 | 3.70 | 0.138 | 0.146 |
| Q | 5.49 | 6.00 | 0.216 | 0.236 |
| S | 6.04 | 6.30 | 0.238 | 0.248 |

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Z8B00003327

SCALE

EUROPEAN PROJECTION

ISSUE DATE
09-07-2010

REVISION
05

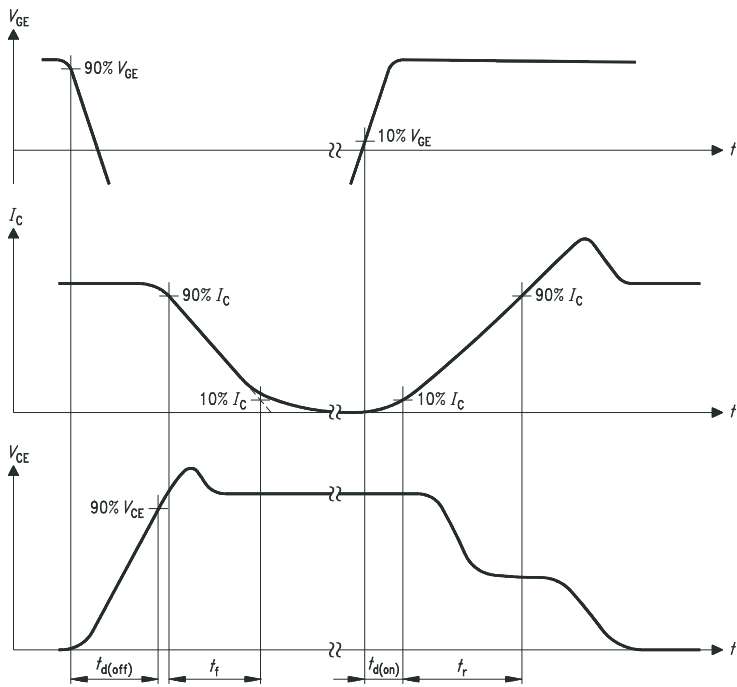


Figure A. Definition of switching times

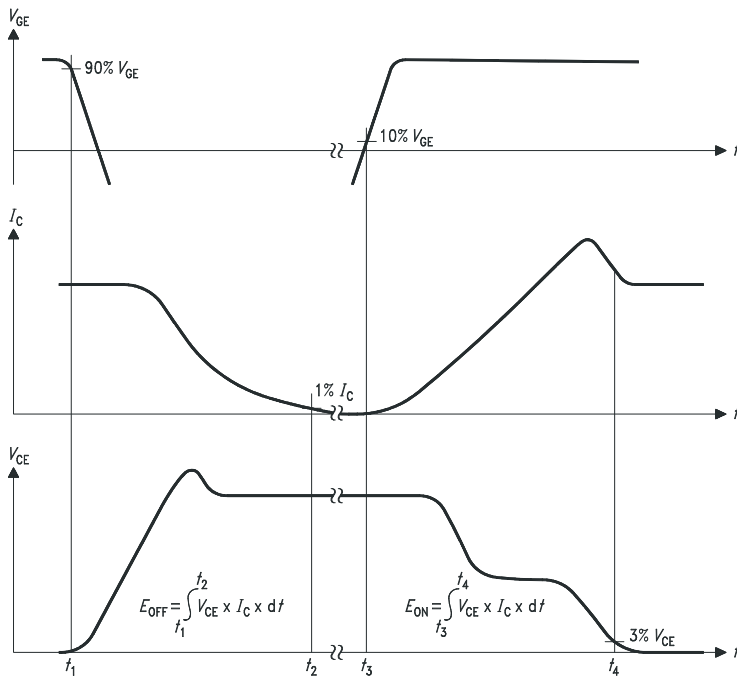


Figure B. Definition of switching losses

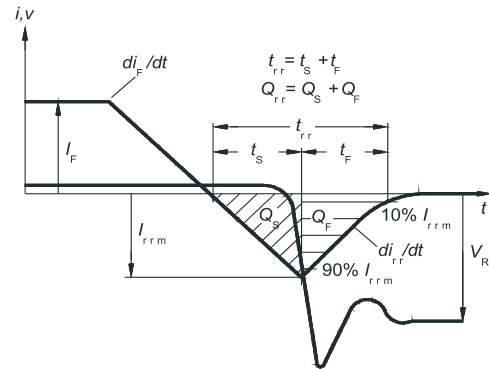


Figure C. Definition of diodes switching characteristics

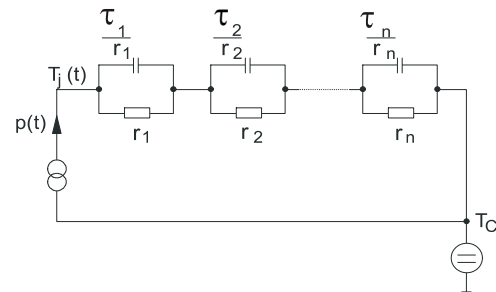


Figure D. Thermal equivalent circuit

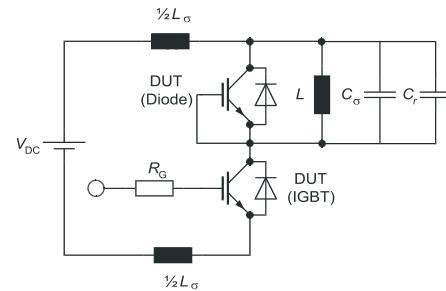


Figure E. Dynamic test circuit
Parasitic inductance L_σ ,
Parasitic capacitor C_σ ,
Relief capacitor C_r
(only for ZVT switching)

Revision History

IGW100N60H3

Revision: 2013-02-07, Rev. 1.2

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|----------|------------|--|
| 1.1 | 2012-07-05 | Preliminary data sheet |
| 1.2 | 2013-02-07 | Preliminary data sheet |

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Your feedback will help us to continuously improve the quality of this document.

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